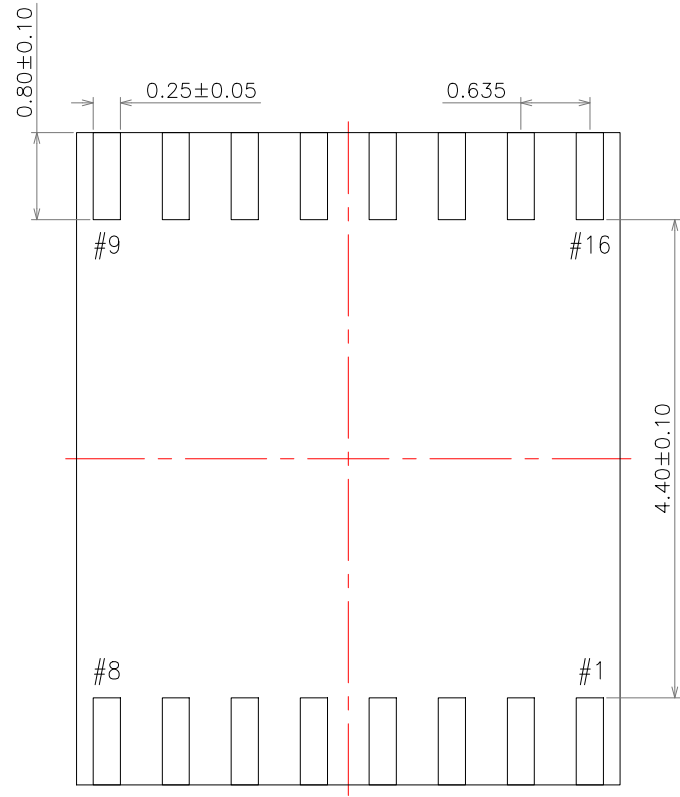
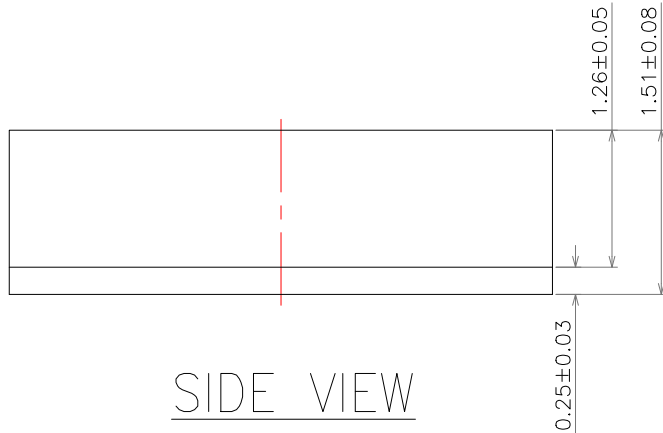


TOP VIEW



BOTTOM VIEW



SIDE VIEW

|  |            |          |             |  |           |        |
|--|------------|----------|-------------|--|-----------|--------|
| DESIGNED BY  | CHECKED BY | CHECK BY | APPROVED BY | TITLE  |           |        |
| K.S.YUN  |            |          |             | <b>PKG OUTLINE DIMENSION<br/>MLSSOP 16LD 0.635 PITCH</b> |           |        |
| 10/01/2023   |            |          |             | UNIT   | TOLERANCE | SCALE  |
| <b>SNPT</b><br>(Semiconductor And Packaging Testing Corporation) |            |          |             | MM   | -         | 1:1    |
|  |            |          |             | DWG NO.  | SPEC NO.  | SHEET  |
|  |            |          |             | POD-MLSSOP-16635   | MLSSOP-01 | 1 OF 1 |